

**HYGO**

**HYG090N04LS1D/U/V**

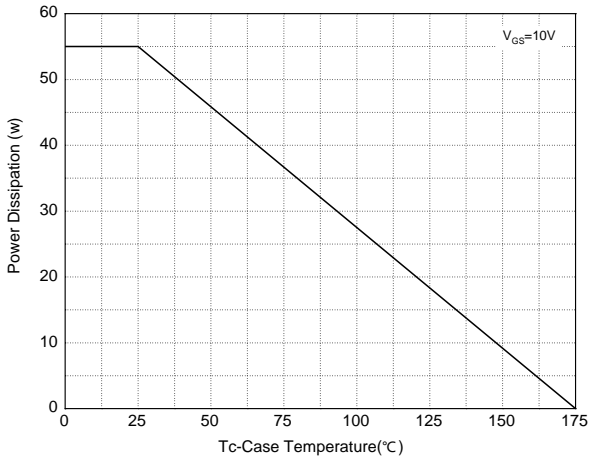
**Electrical Characteristics (Cont.)** (T<sub>c</sub> =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HYG090N04LS1			Unit
			Min	Typ.	Max	
<b>Dynamic Characteristics</b>						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=500KHz	-	2.0	-	
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> = 25V, Frequency=500KHz	-	824	-	pF
C <sub>oss</sub>	Output Capacitance		-	160	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	12.6	-	
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =20V, R <sub>G</sub> =4 Ω, I <sub>DS</sub> =20A, V <sub>GS</sub> =10V	-	7.5	-	ns
T <sub>r</sub>	Turn-on Rise Time		-	31	-	
t <sub>d(OFF)</sub>	Turn-off Delay Time		-	14.7	-	
T <sub>f</sub>	Turn-off Fall Time		-	1.9	-	
<b>Gate Charge Characteristics</b>						
Q <sub>g</sub>	Total Gate Charge(V <sub>GS</sub> =10V)	V <sub>DS</sub> =32V, I <sub>DS</sub> =20A	-	12.3	-	nC
	Total Gate Charge(V <sub>GS</sub> =4.5V)		-	5.9	-	
Q <sub>gs</sub>	Gate-Source Charge		-	3.37	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	1.57	-	
V <sub>plateau</sub>	Gate plateau voltage		-	3.75	-	V

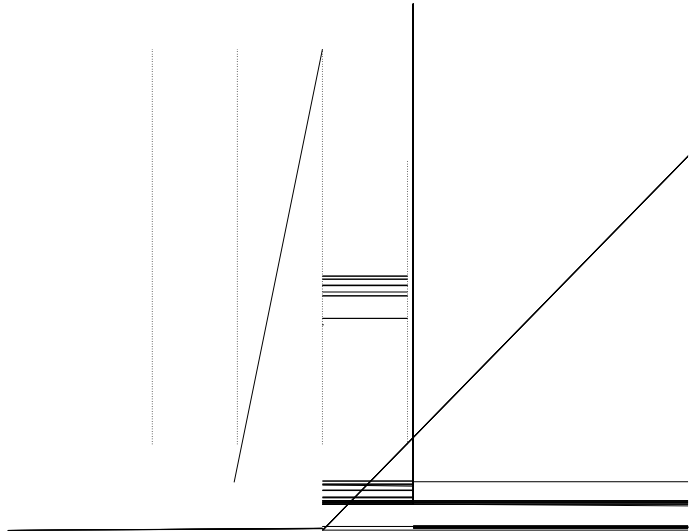
Note: \*Pulse test pulse width 300us duty cycle 2%

**Typical Operating Characteristics**

**Figure 1: Power Dissipation**



**Figure 2: Drain Current**



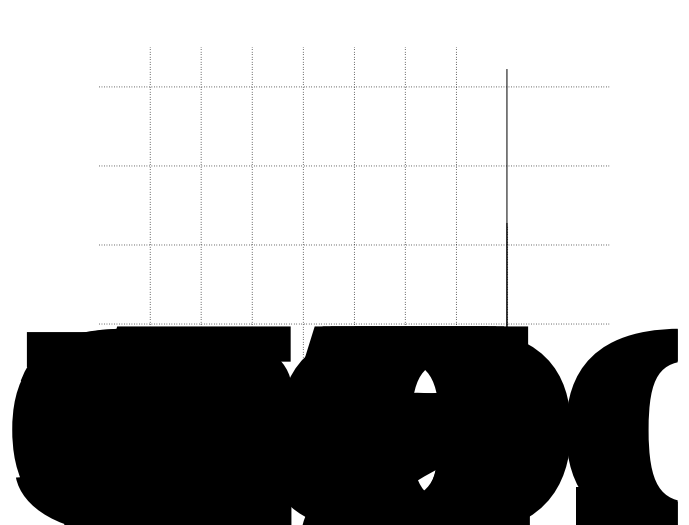
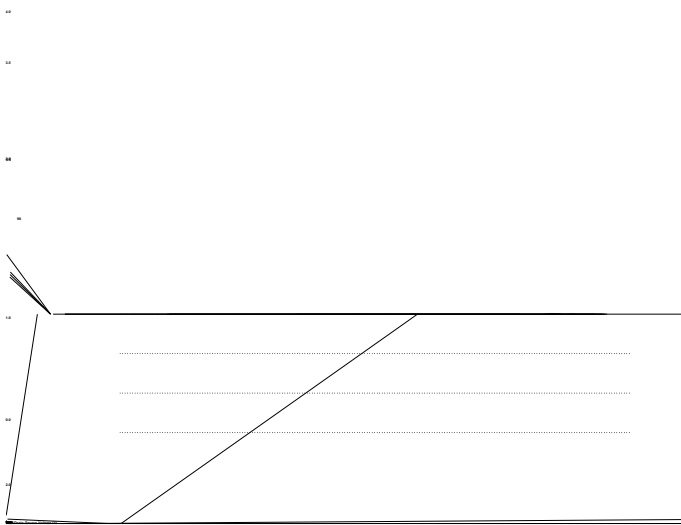
**Figure 3: Safe Operation Area**

**Figure 4: Thermal Transient Impedance**



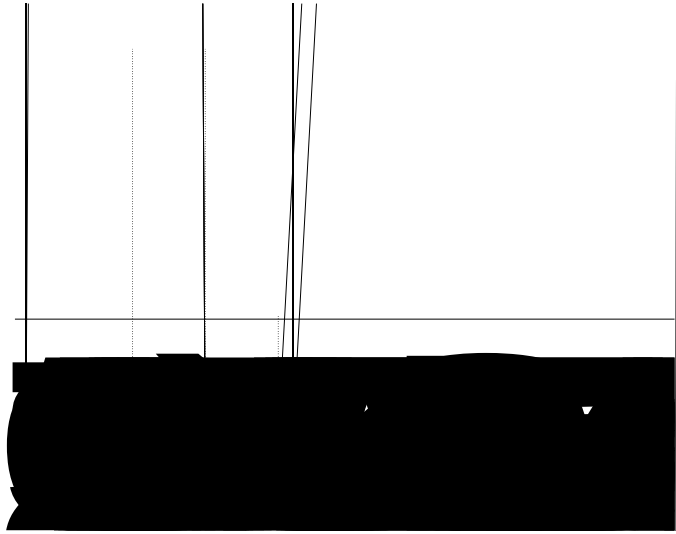
**Figure 5: Output Characteristics**

**Figure 6: Drain-Source On Resistance**

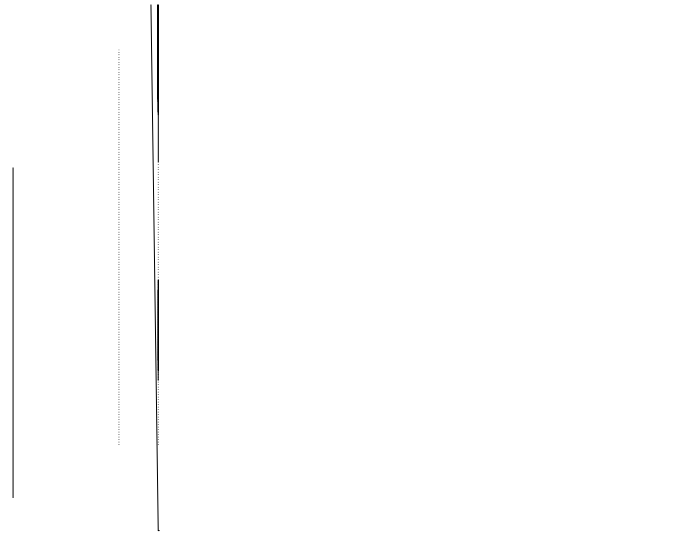


**Typical Operating Characteristics(Cont.)**

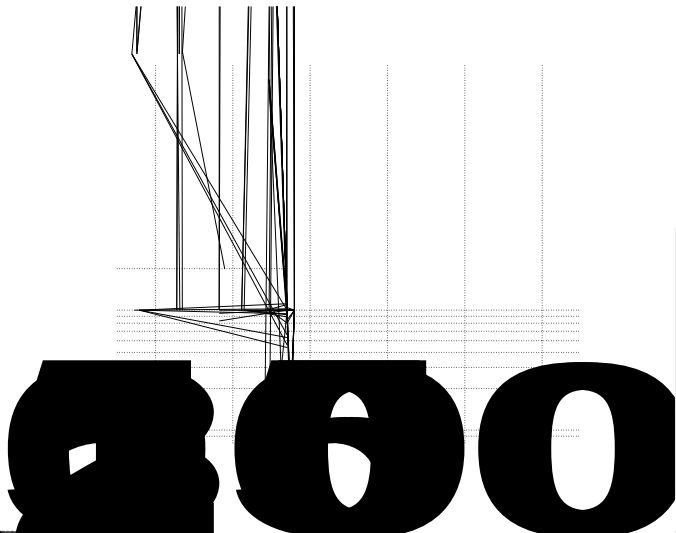
**Figure 7: On-Resistance vs. Temperature**



**Figure 8: Source-Drain Diode Forward**



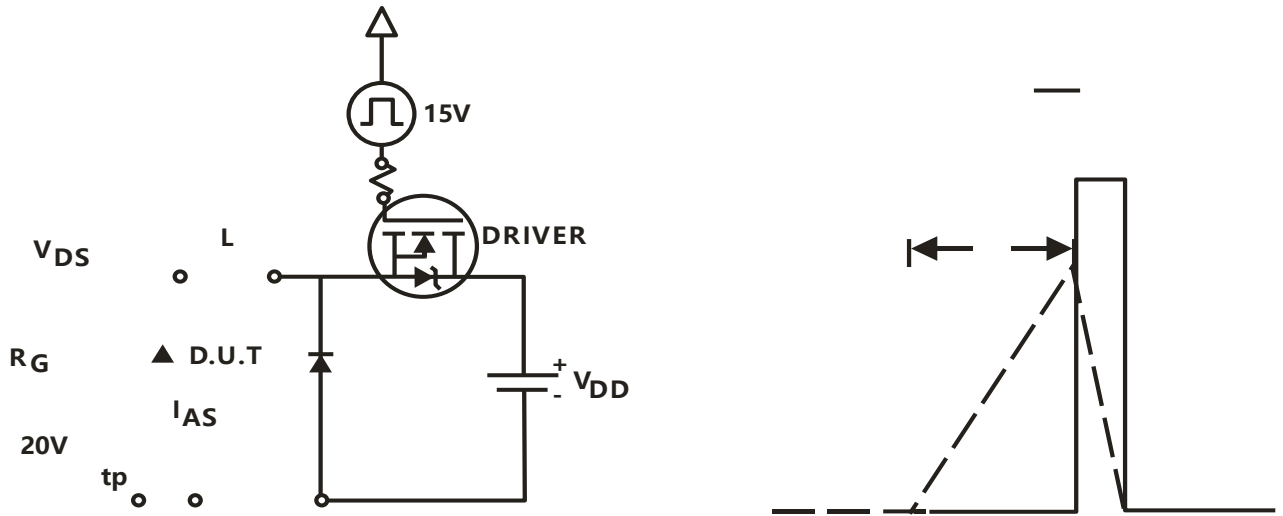
**Figure 9: Capacitance Characteristics**



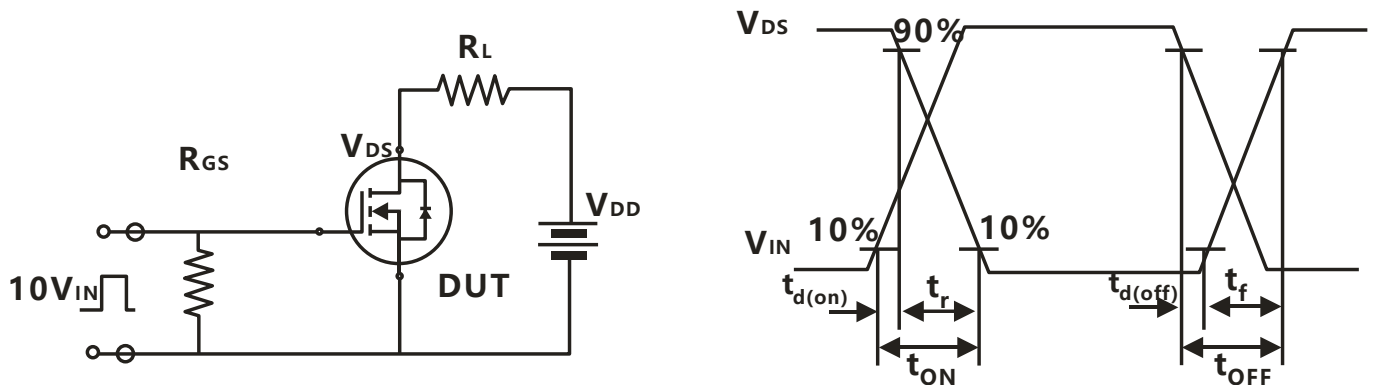
**Figure 10: Gate Charge Characteristics**



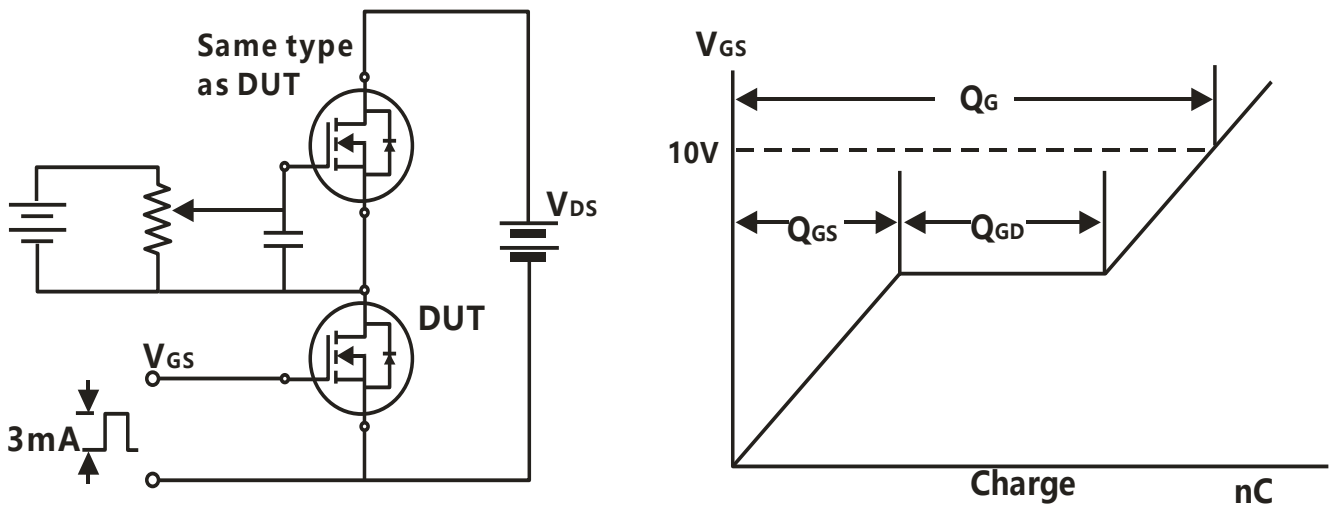
**Avalanche Test Circuit**



**Switching Time Test Circuit**



**Gate Charge Test Circuit**

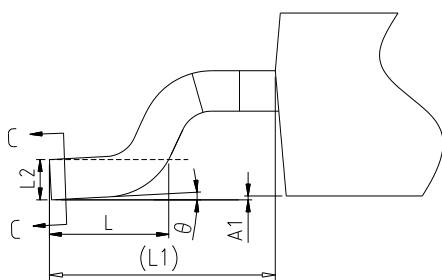
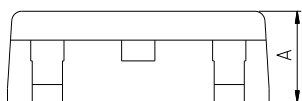
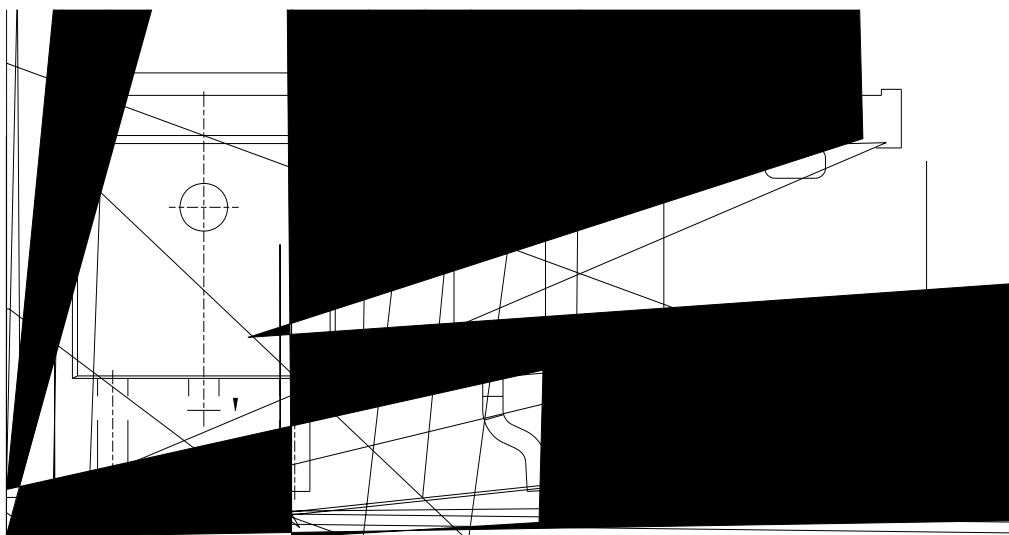


## Device Per Unit

Package Type	Unit	Quantity
TO-252-2L	Tube	75
TO-252-2L	Reel	2500
TO-251-3L	Tube	75
TO-251-3S	Tube	75

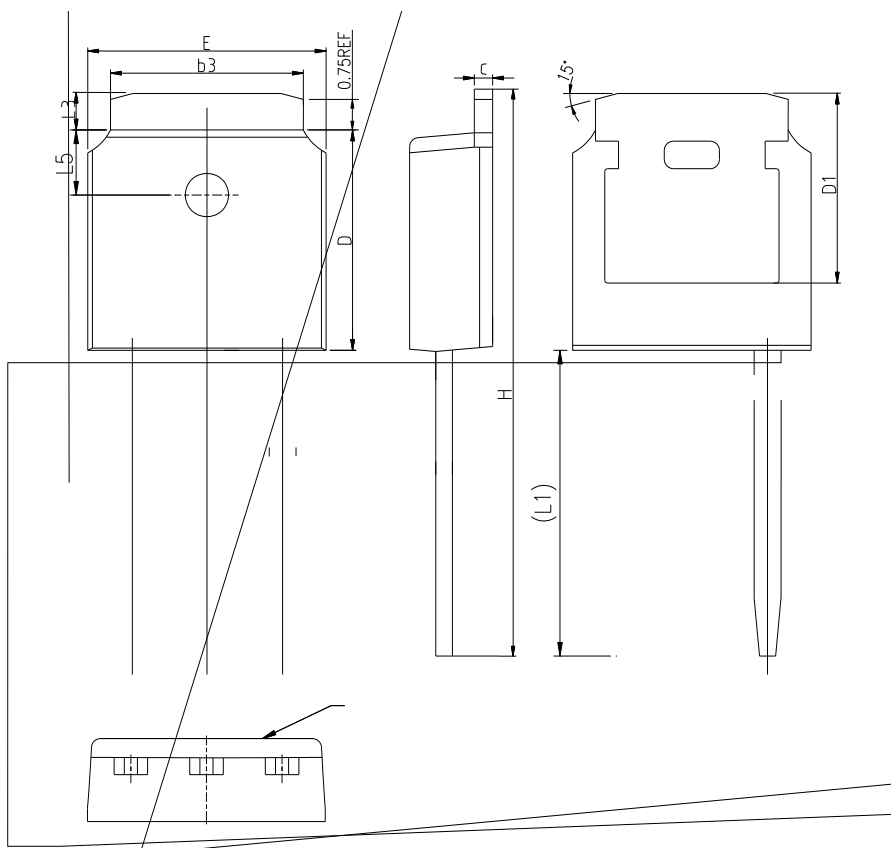
## Package Information

TO-252-2L



COMMON DIMENSIONS			
SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	-	0.12
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
	0°	-	8°

TO-251-3L



COMMON DIMENSIONS			
SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b2	0.00	0.04	0.10
b2'	0.00	0.04	0.10
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	4.30	5.30	6.00
D2	6.92	7.12	7.32
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	16.22	16.52	16.82
L1	9.15	9.40	9.65
L3	0.88	1.02	1.28
L5	1.65	1.80	1.95



TO-251-3S



COMMON DIMENSIONS			
SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.60
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	10.00	11.22	11.44
L1	3.90	4.10	4.30
L3	0.88	1.02	1.28
L5	1.65	1.80	1.95

**Classification Profile**



**Classification Reflow Profiles**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_l$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_p$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_p$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
*Tolerance for peak profile Temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <350	Volume mm 350
2.5 mm	235 °C	220 °C
2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <350	Volume mm 350-2000	Volume mm 2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
2.5 mm	250 °C	245 °C	245 °C

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	168/500 Hrs, Bias @ 150°C
HTGB	JESD-22, A108	168 /500 Hrs.15 218.42 15.6 re7.09 g/312